



Microwave Passive Components, 2nd Edition

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Message from the Guest Editors

Dear Colleagues,

As is well-known, microwave passive components play an important role in the design and application of these devices and systems. Especially with the development of advanced machining technologies, such as the micro-electro-mechanical system (MEMS), 3D printing, and micro-/nano-machining, the machining accuracy and ability of the passive components have been improved greatly. This has made the microwave passive devices/components enter a new stage controlled by information coding. Prof. Guo Liu has organized a Special Issue entitled “Microwave Passive Components”, which received a strong response within the field. Therefore, this Special Issue, entitled “Microwave Passive Components, 2nd Edition”, was created, devoted to continue exploring for research papers and review articles focusing on the theory, modeling, simulation, measurement and applications of passive components, circuits, devices and systems in the microwave, millimeter-wave and terahertz-wave bands.





Editor-in-Chief

Message from the Editor-in-Chief

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